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2823

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IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Applicant : Richard SPITZ et al.
Serial No. : 09/914,404
Filed : December 13, 2001
For : **METHOD FOR PRODUCING HEAVILY-DOPED
SEMICONDUCTOR COMPONENTS**
Group Art Unit : 2823
Examiner : M. ESTRADA

Commissioner for Patents
Washington, D.C. 20231

I hereby certify that this correspondence is being deposited with the
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on

Date AUGUST 22, 2002

TRANSMITTAL

Signature

Chips Kenyon
KENYON & KENYON

SIR:

Transmitted herewith for filing in the above-identified patent application is an
Amendment (the three-month response date for which is August 22, 2002).

While no fee is believed to be due, the Commissioner is authorized to charge
any additional fees, including any extension fees under Rule 136(a), or credit any
overpayment to Deposit Account No. 11-0600. A duplicate copy of this transmittal letter is
enclosed for that purpose.

Respectfully submitted,

Dated: AUGUST 22, 2002

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